

Application No.: 10/612,804
Amendment dated: April 11, 2005
Reply to Office Action dated: January 11, 2005

REMARKS/ARGUMENTS

Claims 3-4 and 18-27 are pending in the application.

Claims 23-27 were rejected under 35 U.S.C. §102(b) as being anticipated by Papathomas et al., U.S. Patent No. 5,656,862 (hereinafter "Papathomas"). Claims 3-4 and 18-22 were allowed.

Figure 1 has been designated and identified as Prior Art to comply with the Examiner's request. Replacement sheets 1-13 are attached following page 7 of this paper.

Claim Rejections Under 35 U.S.C. §102(b)

Claims 1, 5, 7, 14, and 18 were rejected under 35 U.S.C. §102(b) as being anticipated by Papathomas. Papathomas generally discloses a solder interconnection encapsulant, encapsulated structure and method for its fabrication and use (*See Abstract*).

Papathomas does not disclose filler particles dispersed in the benzocyclobutene, as recited by claims 23 and 25. The relevant sections of Papathomas state:

In the figure, numeral 1 represents a semiconductor chip joined to the chip carrier 2 by solder bumps 3 mated to pads 4. I/O can be in the form of pins extending and protruding from the carrier 2, with a small portion of the pins protruding from the other side of the carrier for carrying current thereto.

(*See Papathomas, Col. 3, Lines 51-53*).

The encapsulant 5 pursuant to the present invention provides for essentially void free encapsulation of the solder connections thereby assuring highly reliable devices and fills the gap forming a uniform fillet around the chip as well as covering the pin heads, circuits, vias, or solder masks under the device (not shown).

(*See Papathomas, Col. 3, Lines 62-67*).

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In other words, solder bumps 3 are surrounded by an encapsulant 5, as opposed to filler particles dispersed in the benzocyclobutene. Therefore, Papathomas does not disclose filler particles dispersed in the benzocyclobutene. Applicants respectfully submit, therefore, that elements of claim 23 and 25 are neither shown nor suggested by the cited reference. Claims 24 and 26-27 depend from claims 23 and 25, respectively. Accordingly reconsideration and withdrawal of the rejection of claims 23-27 under 35 U.S.C. §102(b) is respectfully requested.

For all the above reasons, the Applicant respectfully submits that this application is in condition for allowance. A Notice of Allowance is earnestly solicited.

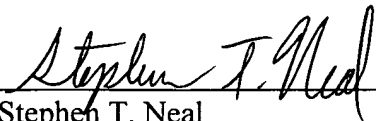
The Commissioner is hereby authorized to charge any additional fees or credit any overpayments under 37 C.F.R. §1.16 or §1.17 to Deposit Account No. **11-0600**.

The Examiner is invited to contact the undersigned at (408) 975-7500 to discuss any matter concerning this application.

Respectfully submitted,

KENYON & KENYON

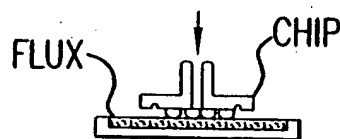
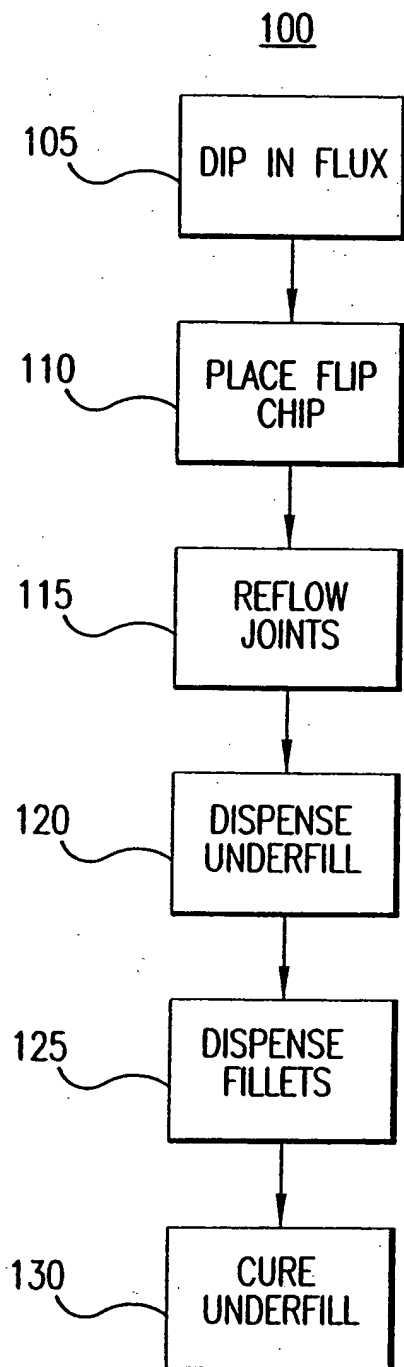
Dated: April 11, 2005

By: 
Stephen T. Neal
(Reg. No. 47,815)
Attorneys for Intel Corporation

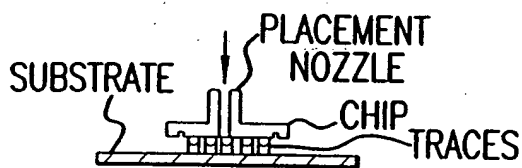
KENYON & KENYON
333 West San Carlos St., Suite 600
San Jose, CA 95110

Telephone: (408) 975-7500
Facsimile: (408) 975-7501

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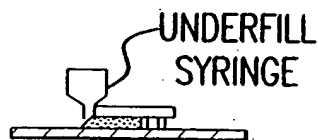
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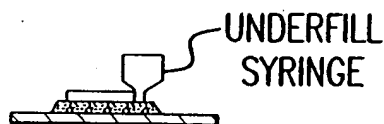
2. PLACE FLIP CHIP



3. REFLOW EUTECTIC JOINTS



4. DISPENSE UNDERFILL



5. DISPENSE FILLETS



6. CURE UNDERFILL

FIG. 1
(Prior Art)

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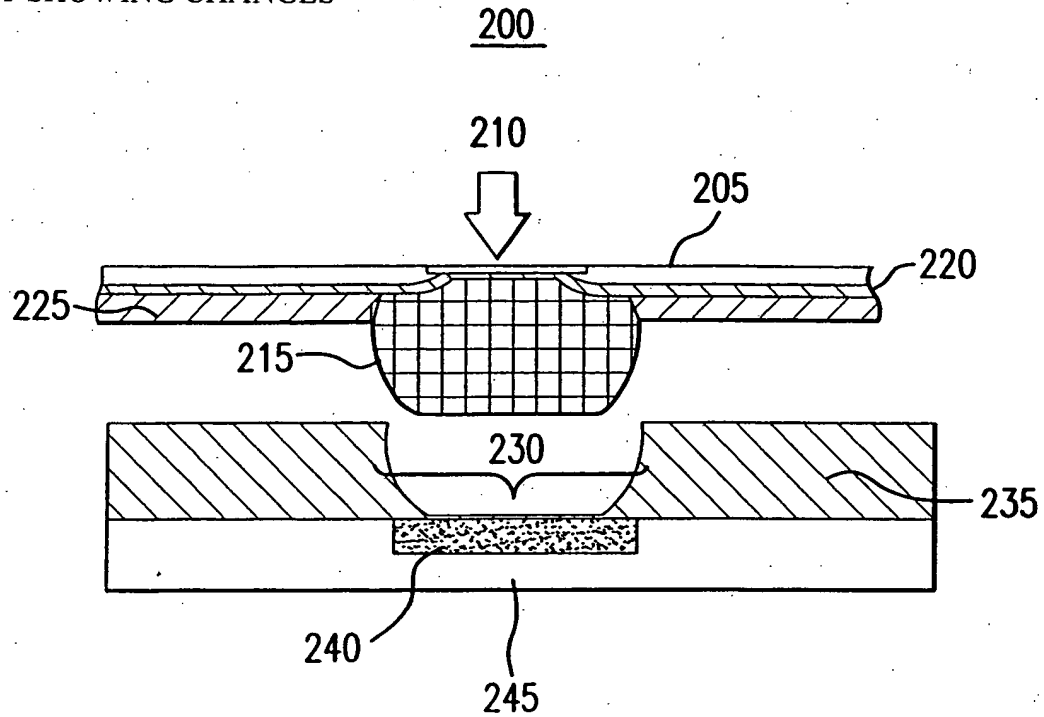


FIG. 2

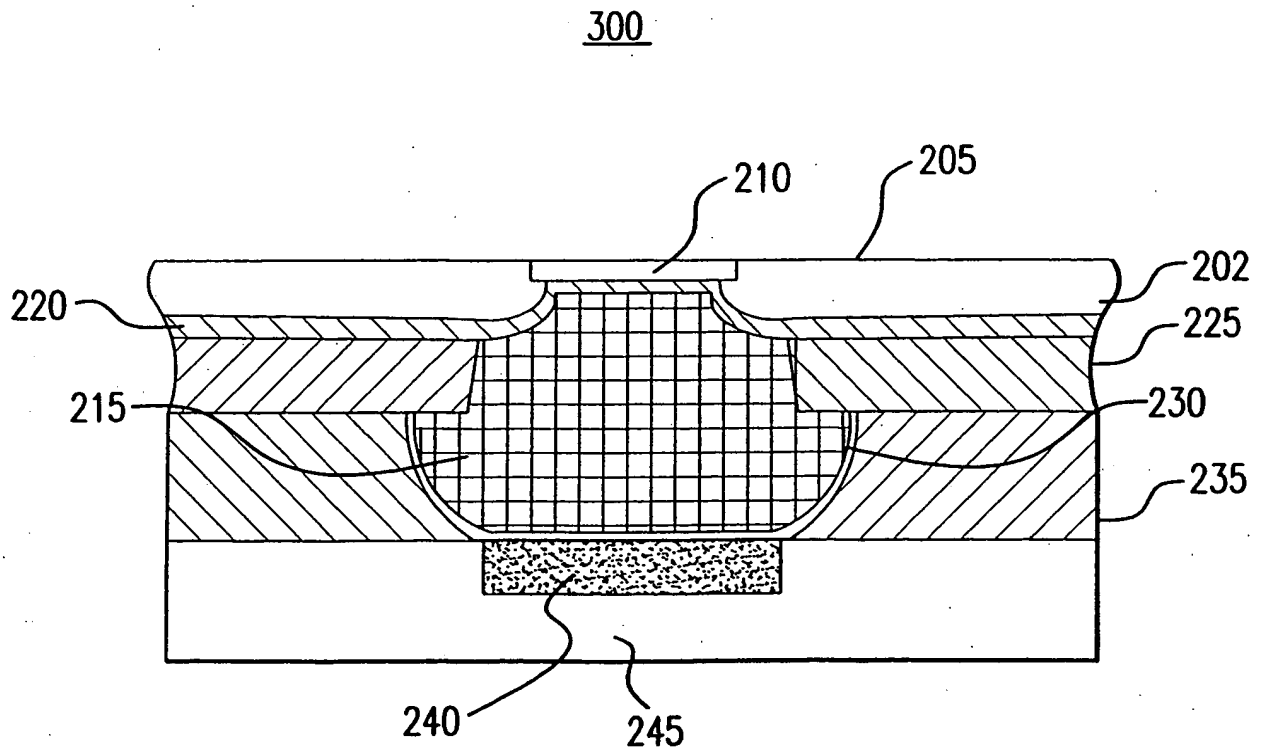


FIG. 3

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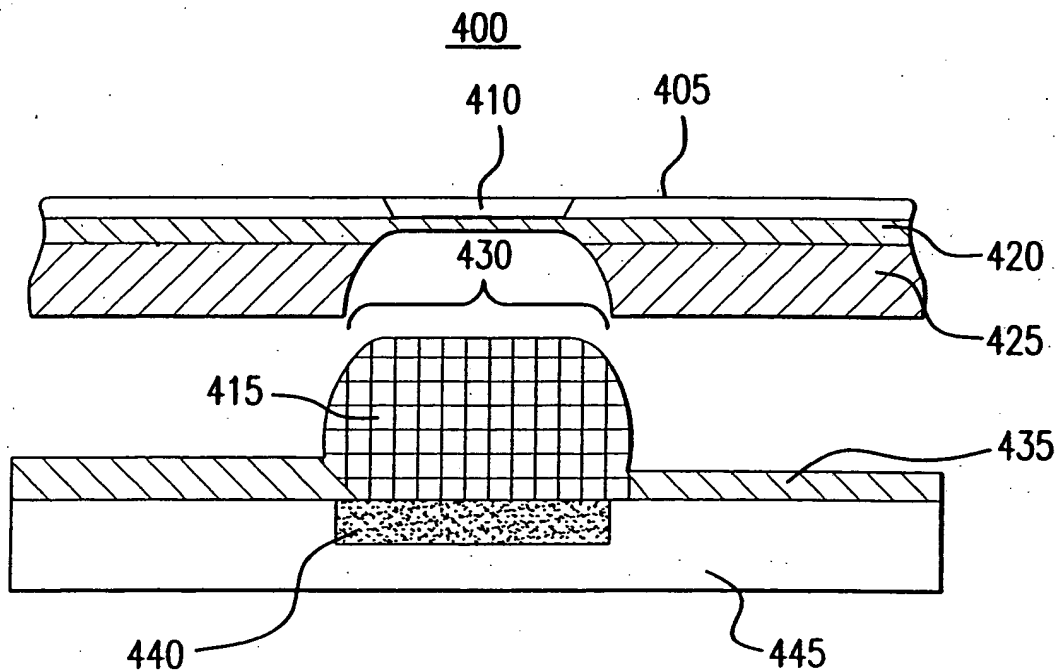


FIG.4

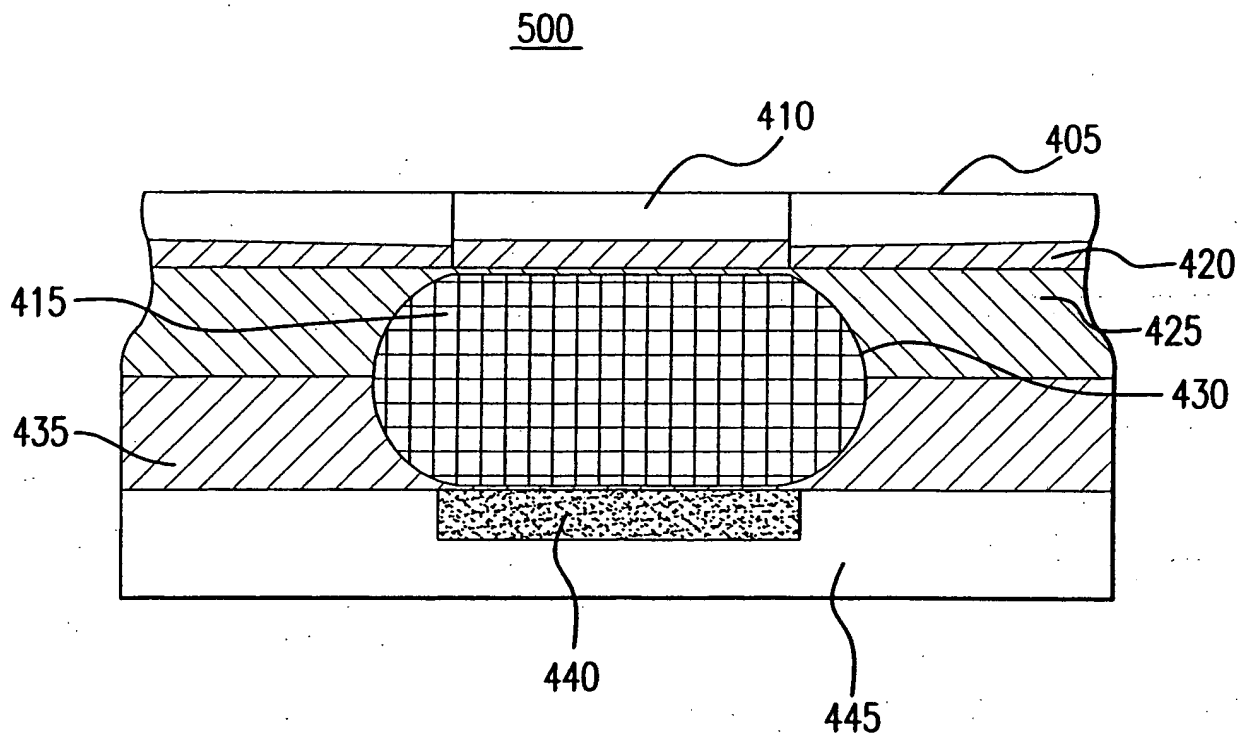


FIG.5

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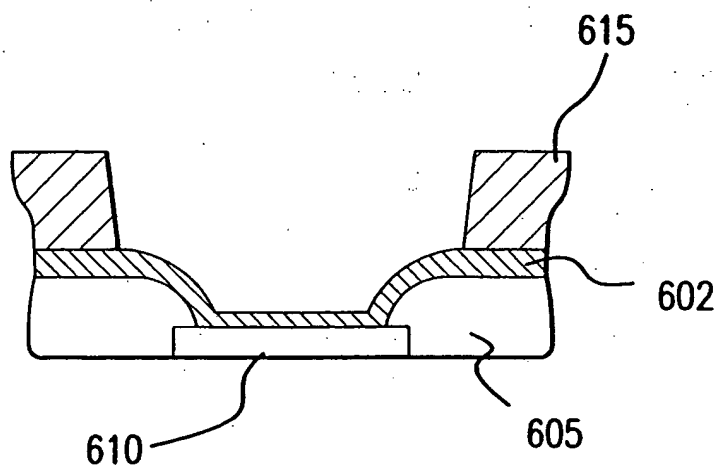


FIG. 6

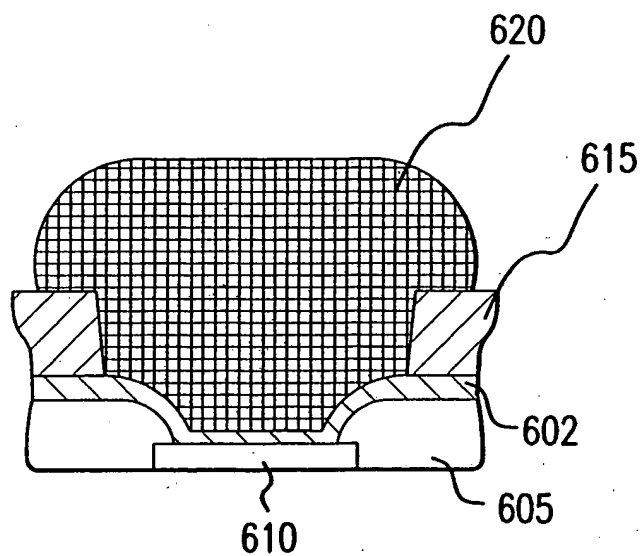


FIG. 7

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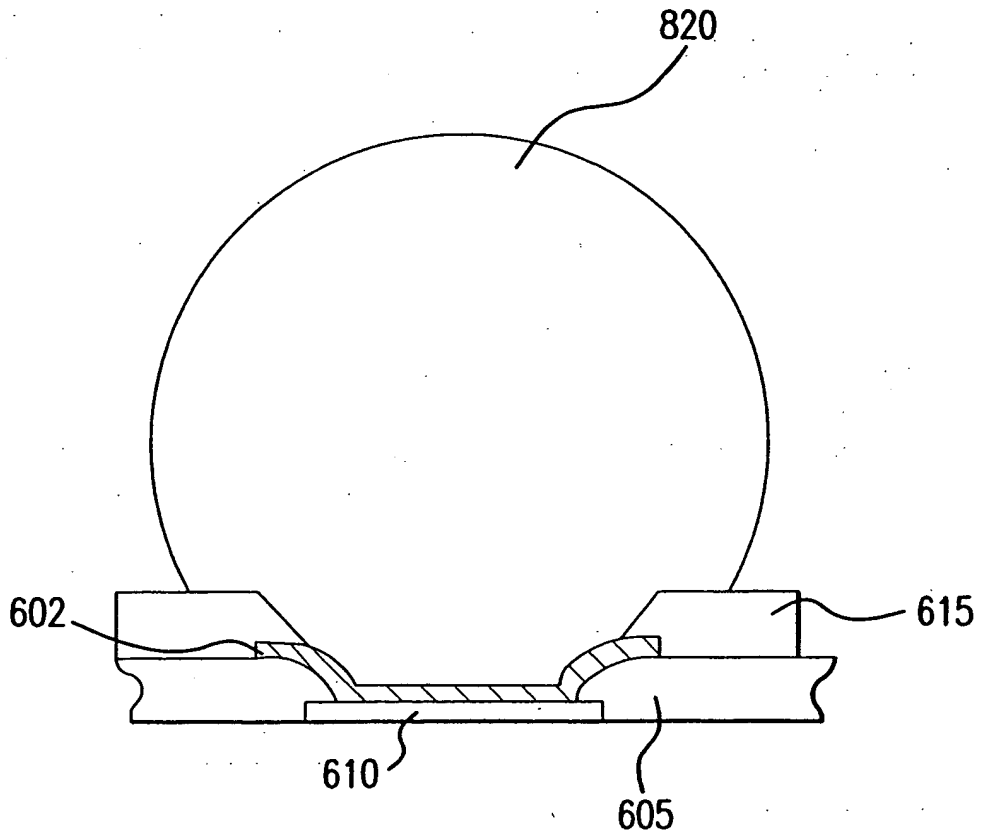


FIG.8

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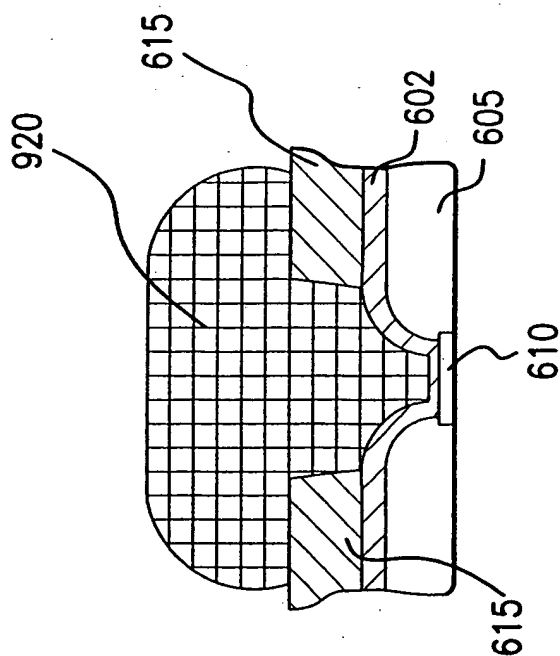


FIG. 9A

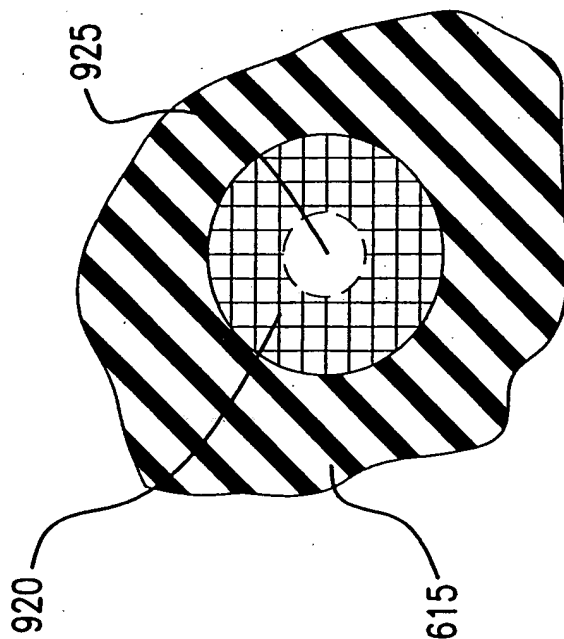


FIG. 9B

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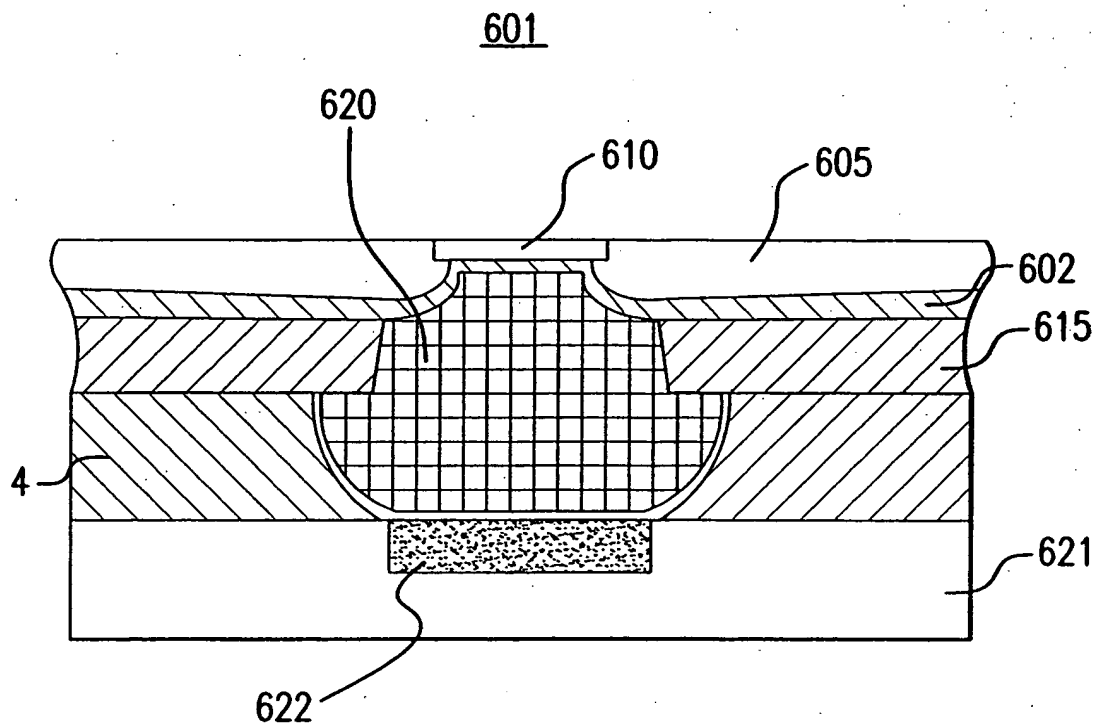


FIG. 10

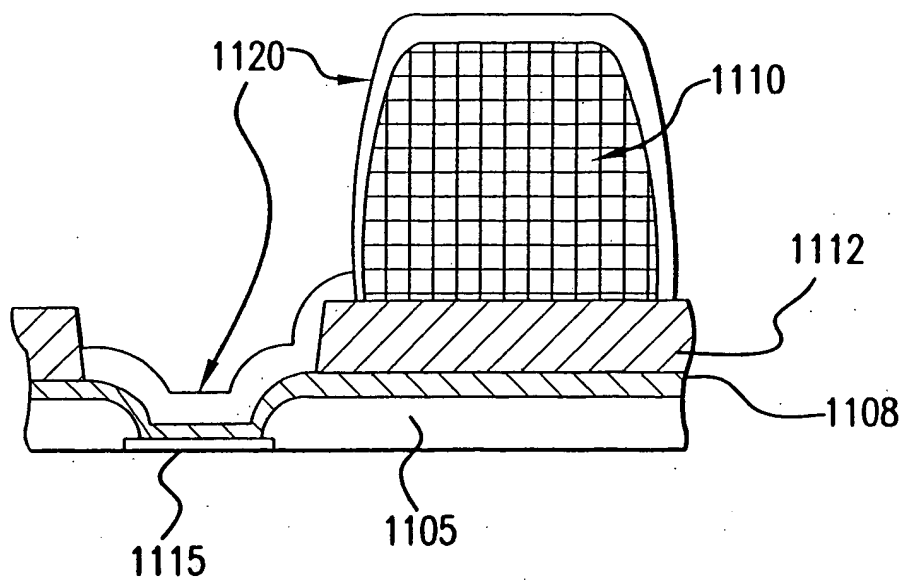


FIG. 11

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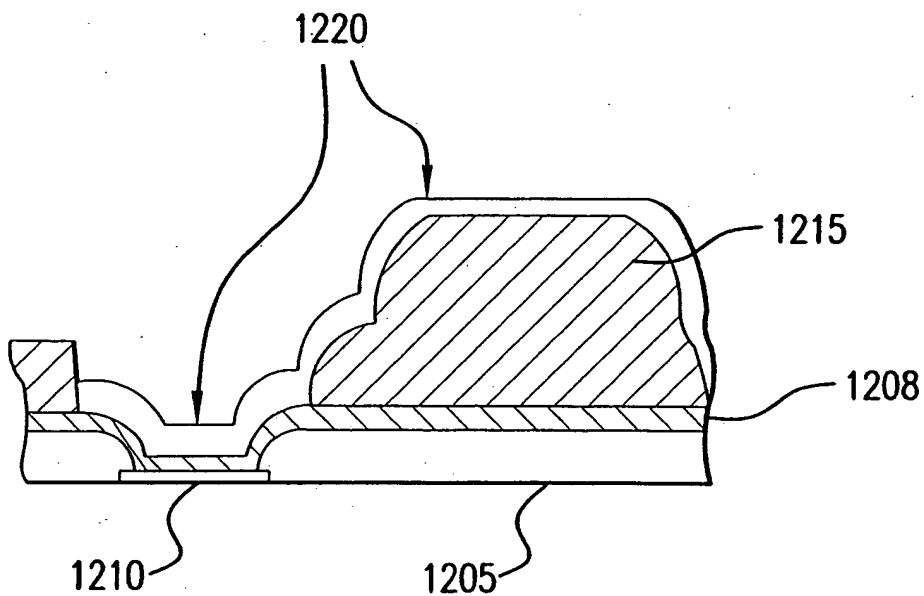


FIG. 12A

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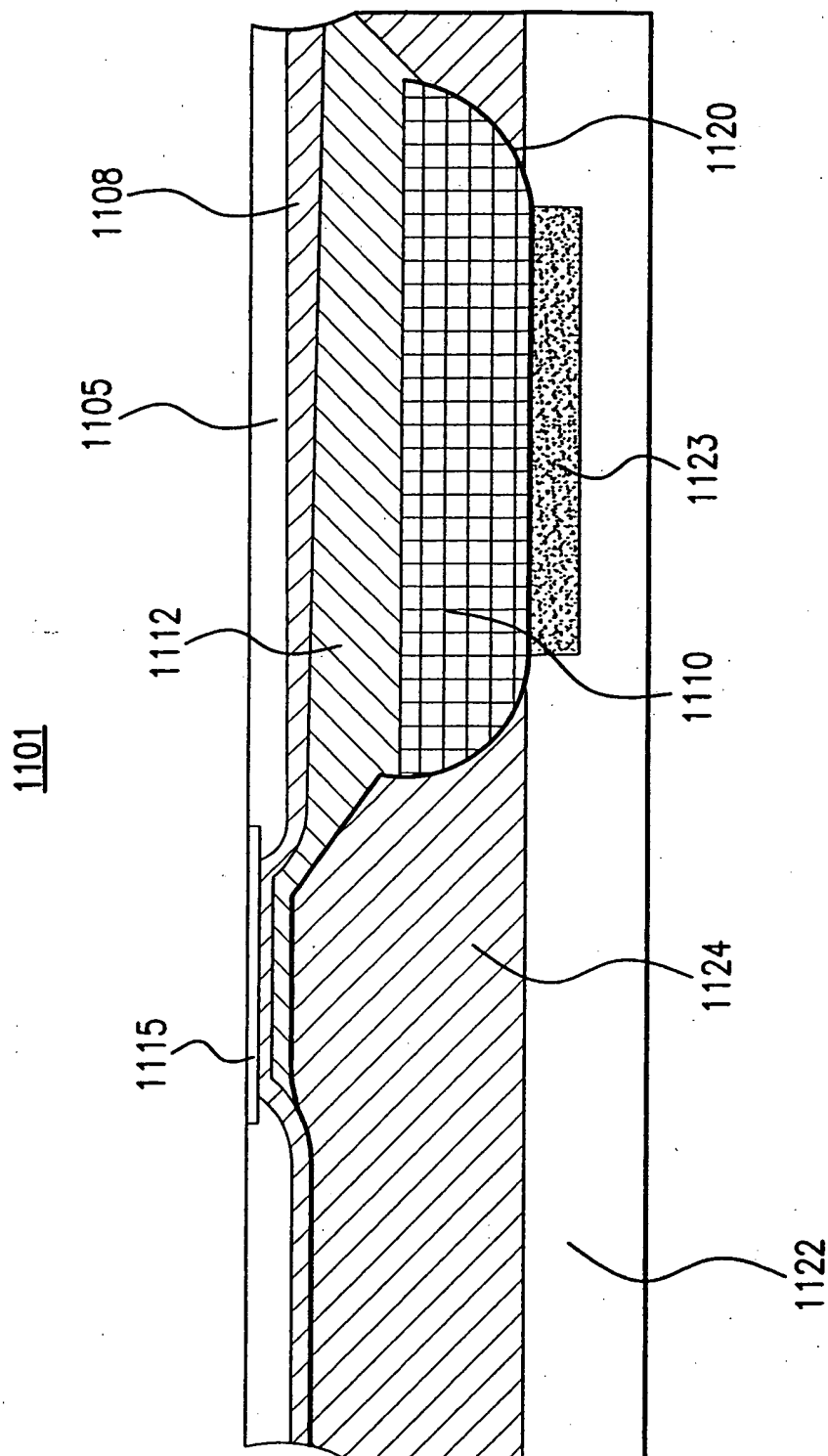


FIG. 12B

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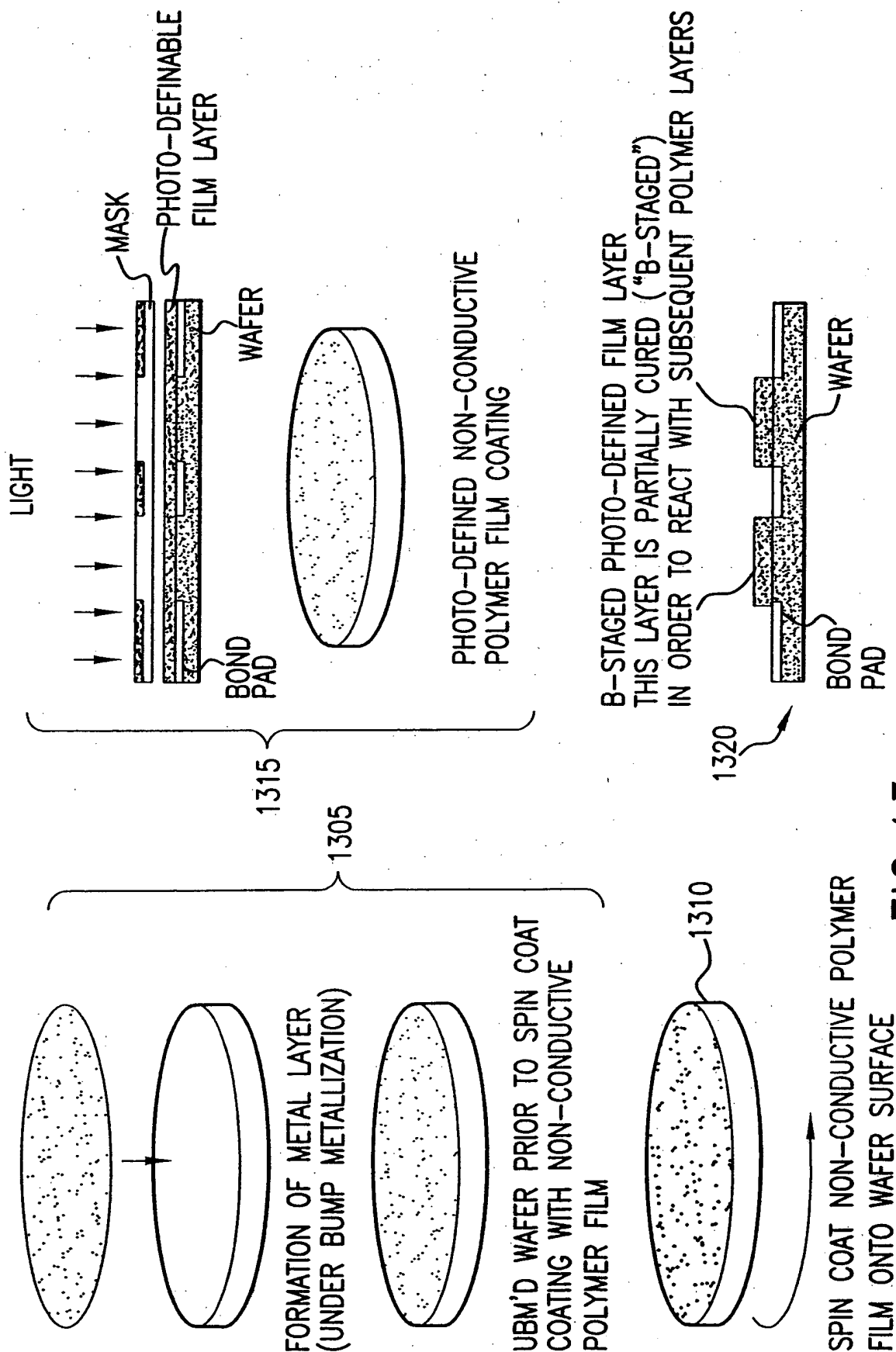


FIG. 13

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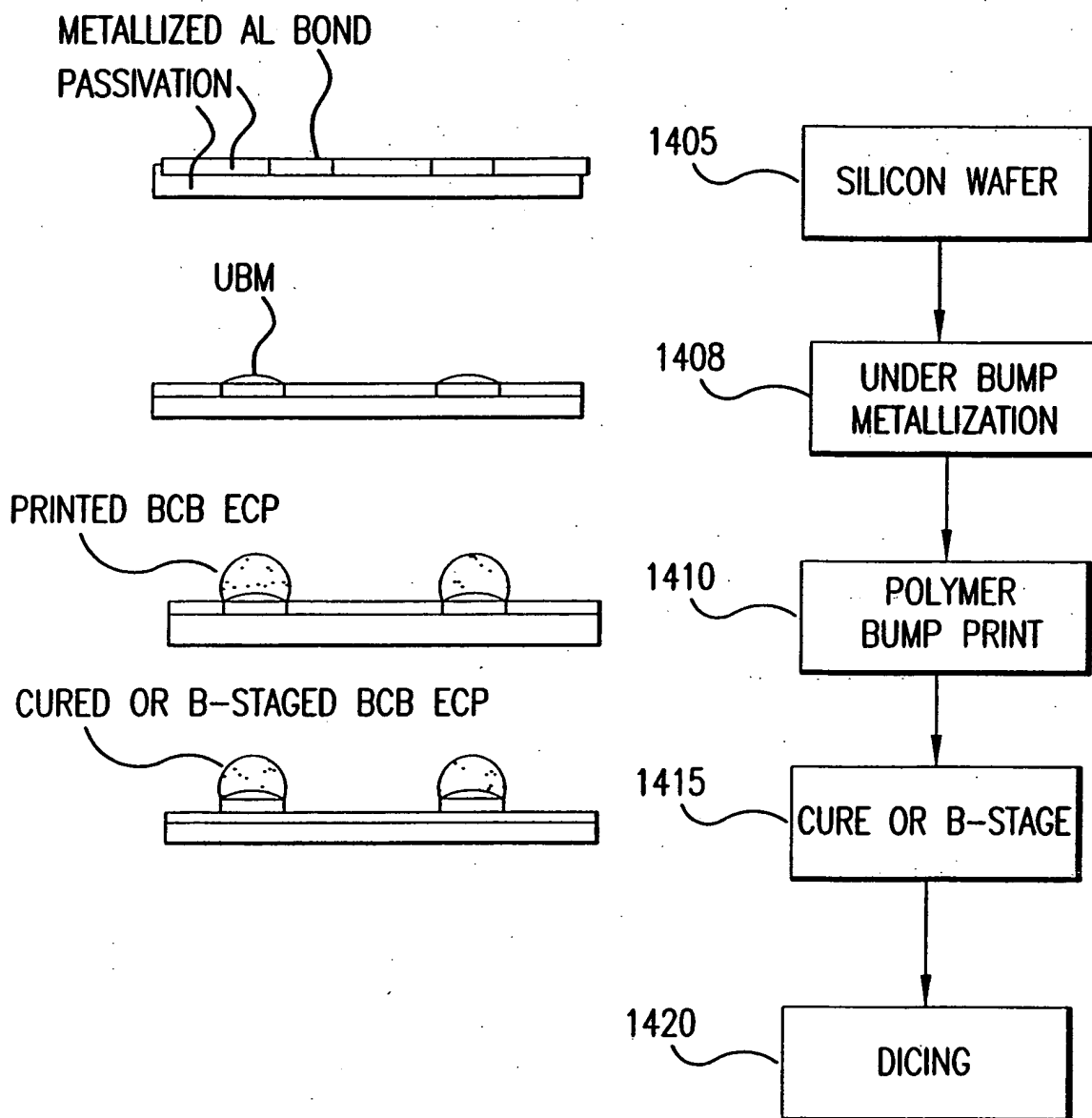


FIG.14A

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1412

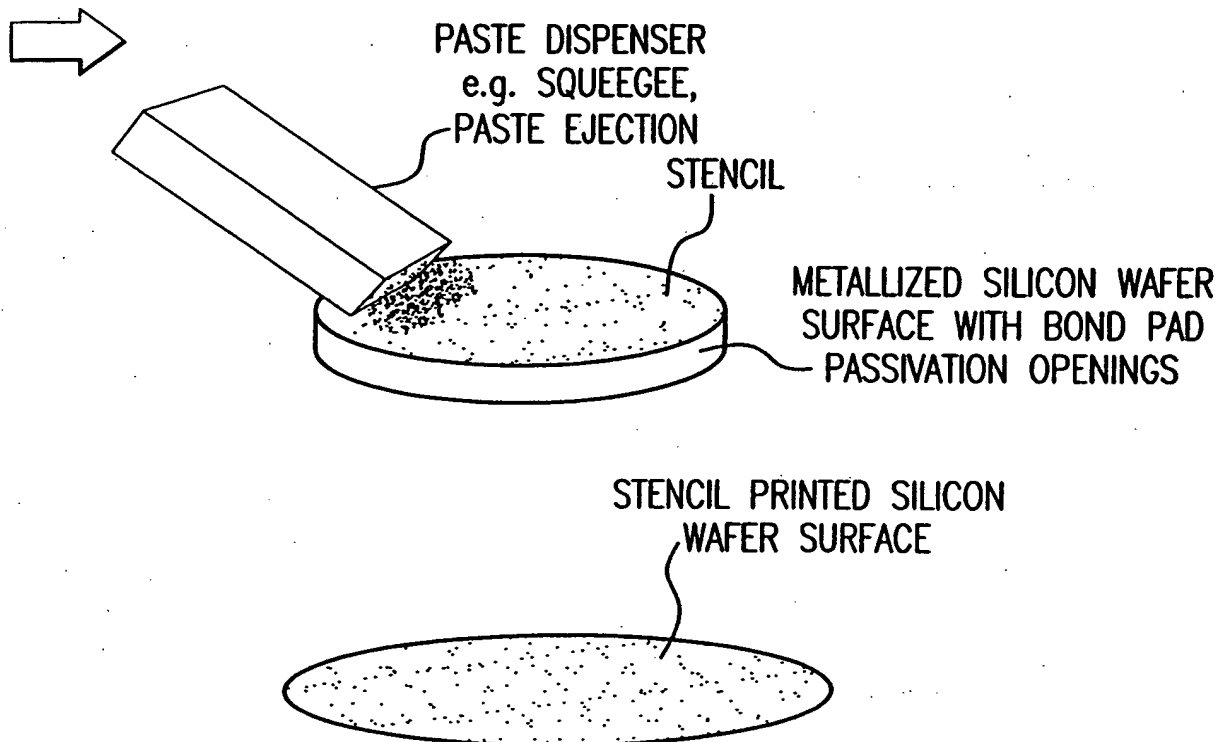


FIG. 14B

1500

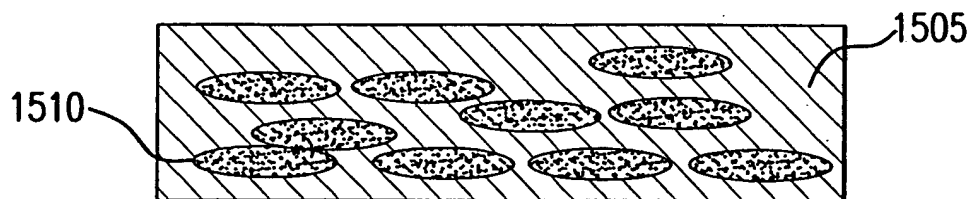


FIG. 15

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1600

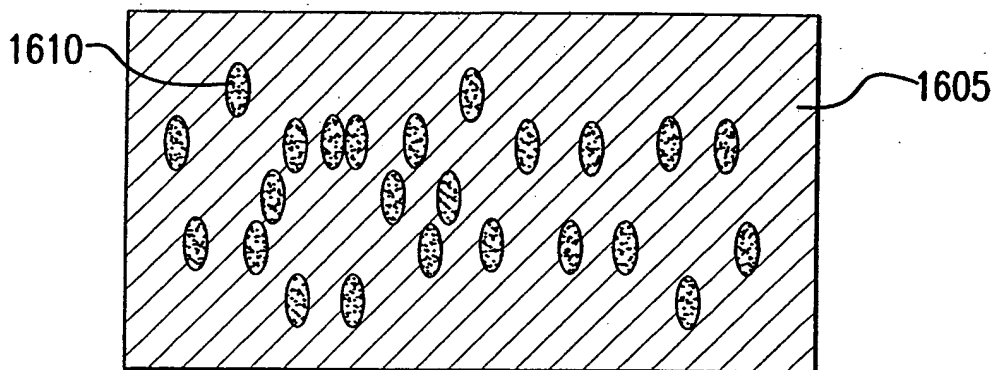


FIG. 16

1700

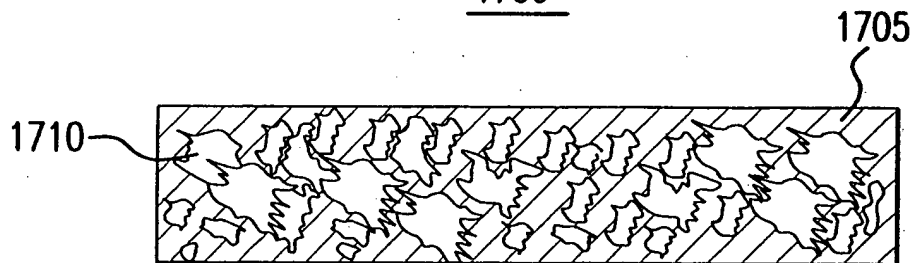


FIG. 17